



x500 15.0kV SE 10µm JEOL SEM WD 6mm

# ICHSF21 INTERNATIONAL CONFERENCE ON HIGH SPEED FORMING

## *A MICRO-MECHANICAL AND MICROSTRUCTURAL ANALYSIS AT THE JOINT INTERFACE BETWEEN DISSIMILAR MATERIALS IN MAGNETIC PULSE WELDING (MPW)*

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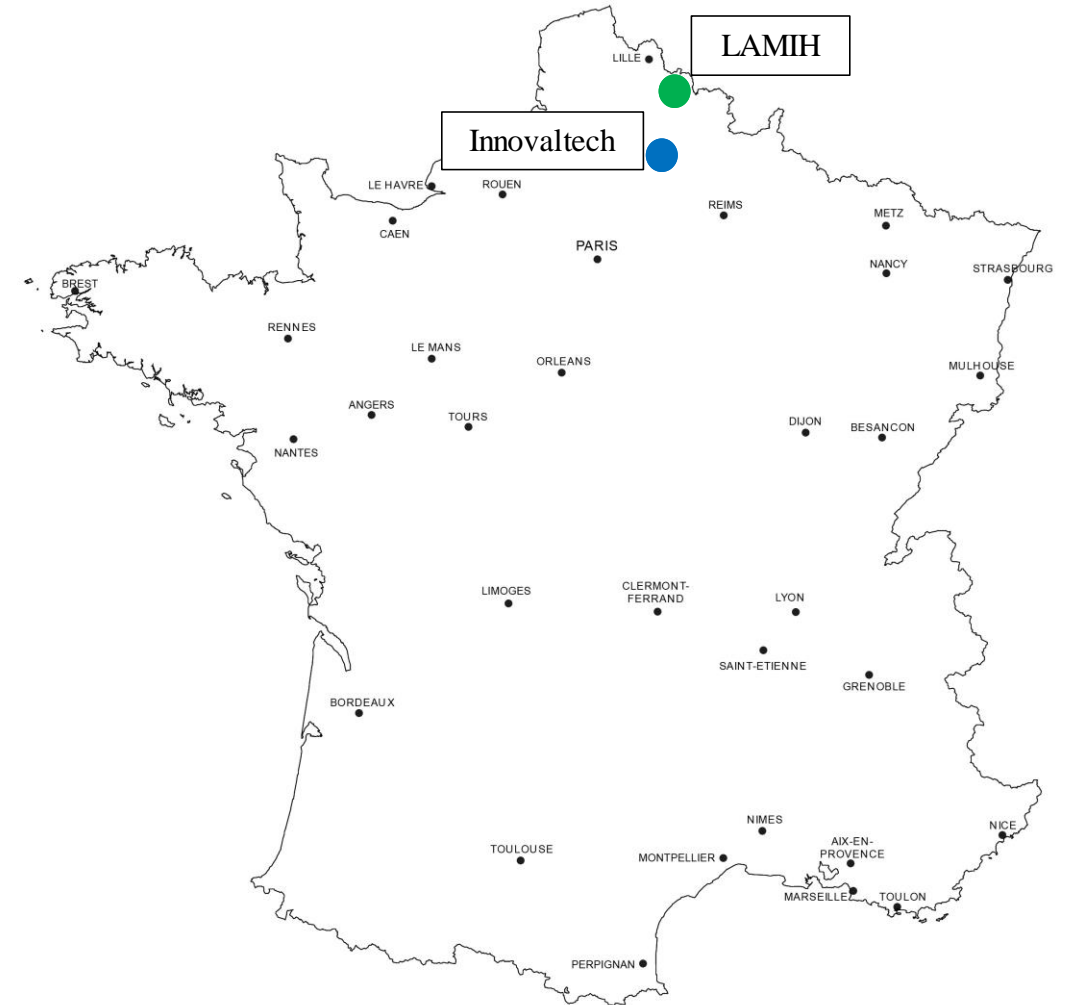
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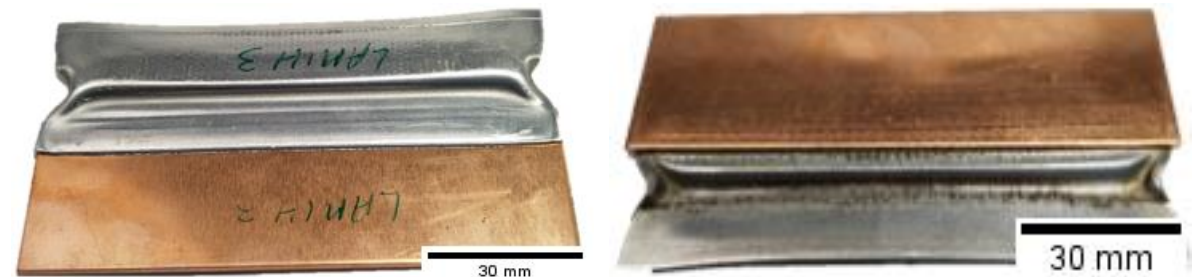
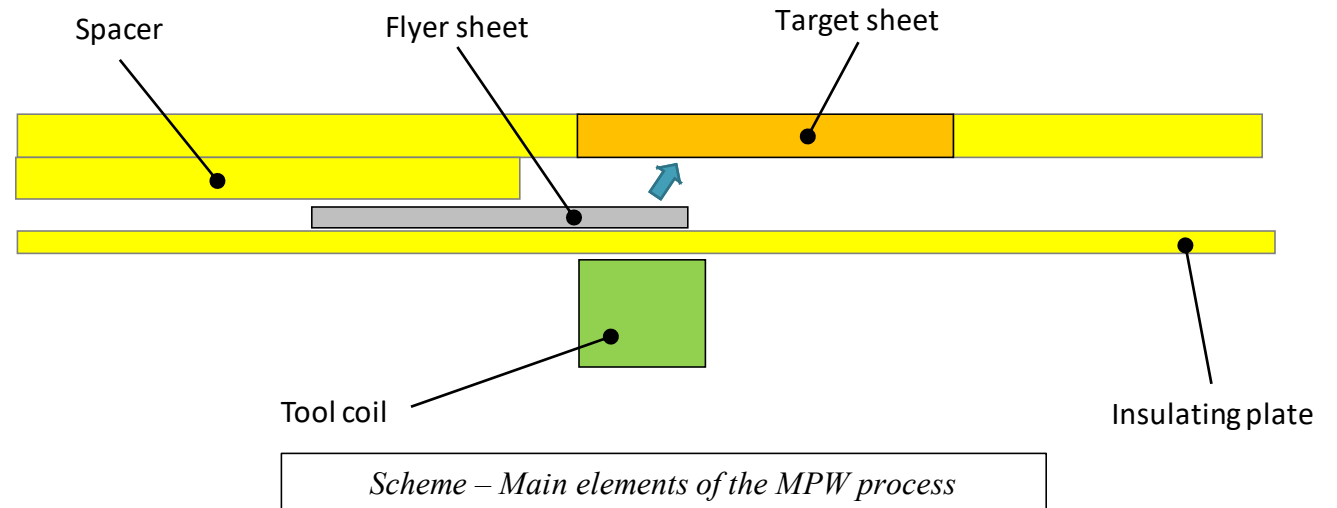
# Introduction - Presentation

- Laboratory LAMIH
  - 4 departments – Around 250 members
- Location: Valenciennes (Hauts-de-France region)
- Partnership with Innovaltech



# Introduction - Overview

- Target of the presentation:
  - Magnetic Pulse Welding (MPW) interface
  - Microstructural properties
  - Mechanical properties
  
- MPW parameters:
  - Materials couple:
    - Copper and copper (Cu/Cu)
    - Aluminum and copper (Al/Cu)
  - Process parameters:
    - Flyer: 1 mm - Base: 2 mm
    - Energy: 19.4 kJ
    - Spacing: 2 mm



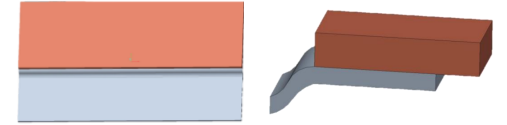
Al/Cu plate sample welded by MPW



# Introduction - Welding interface

- Several kind of interface along the welding seam (especially for dissimilar materials):

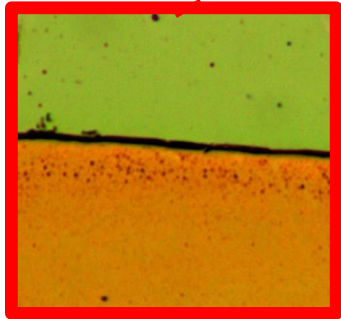
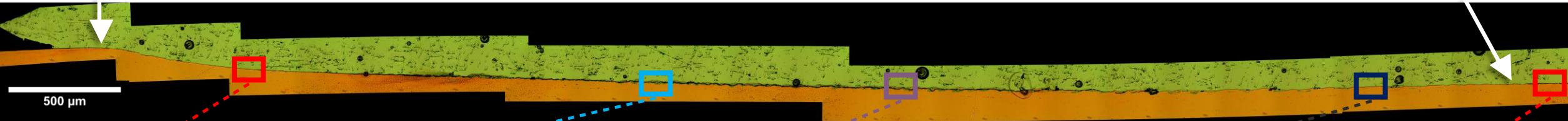
- IMC: Intermetallic compound (example :  $\text{Al}_2\text{Cu}$ )



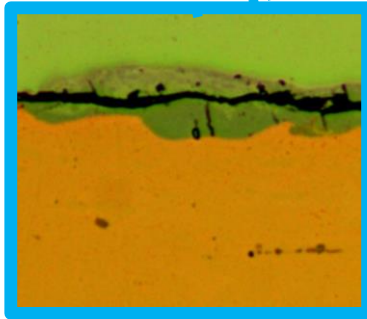
Start of the welding

Stitched image from optical microscope – Interface Al/Cu plates sample n°3 – D welded by MPW

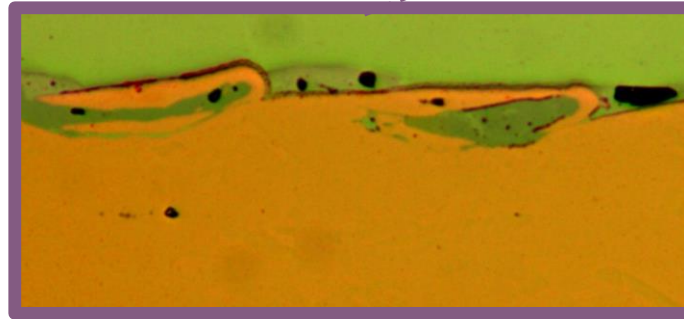
End of the welding



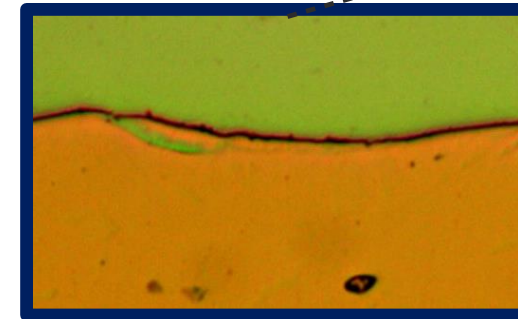
(a) – Unwelded area and no IMC



(b) – Unwelded (cracked) area with IMC



(c) – Welded area with IMC



(d) – Welded area without IMC



(e) – Same as (a)

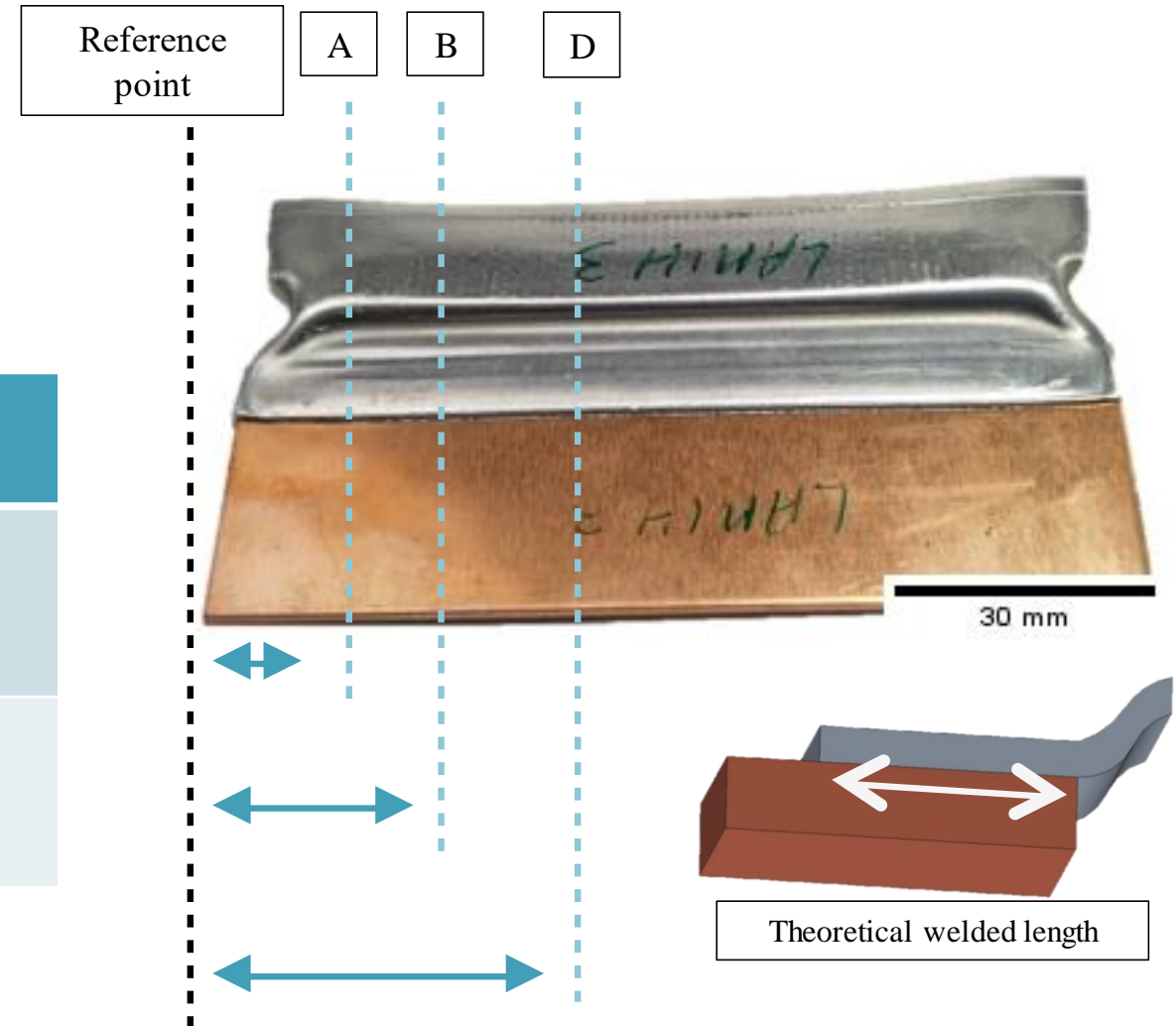
# Introduction - Welding interface

- Important to determine the effective area for the welding
- Effective welding “length” is locally varying

$$\text{Effective welding length} = \frac{\text{Welded length (with and without IMC)}}{\text{Length of the theoretical welded length}}$$

Section localization	A	B	D
Position to reference (mm)	12	20	36
Effective welding “length”	22%	39%	37%

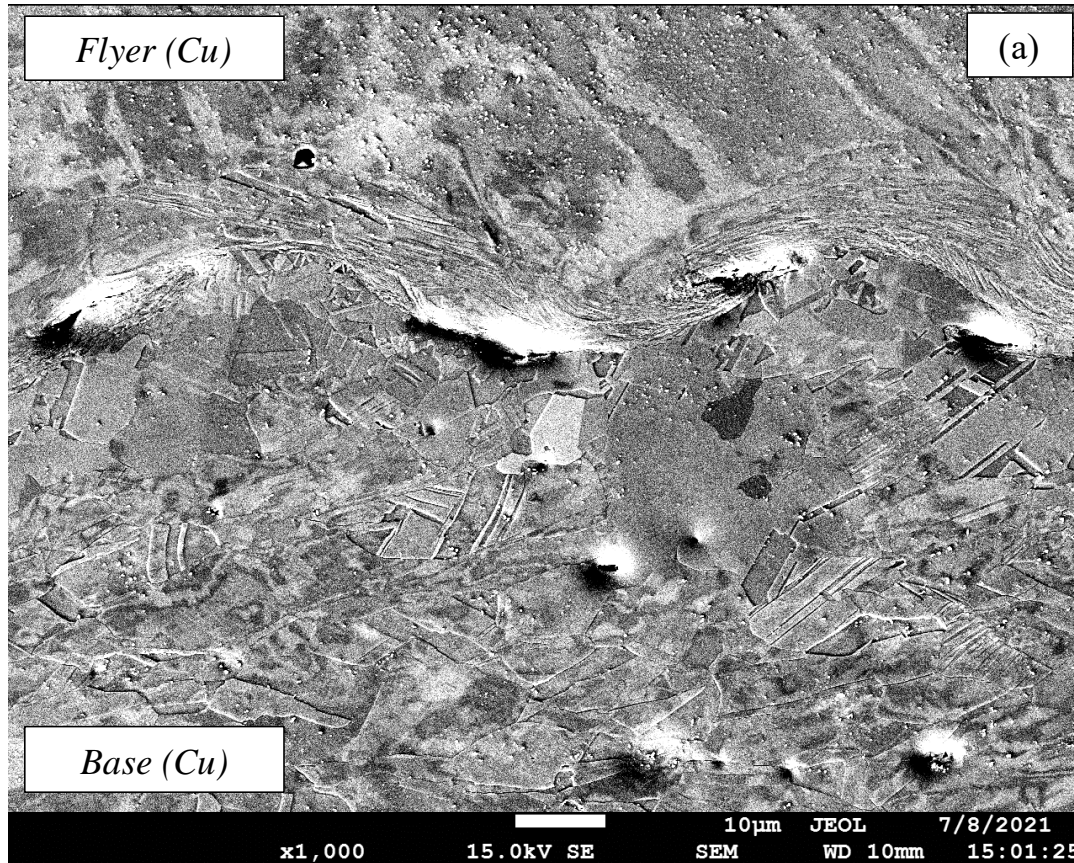
Scheme – Position of the sections on a Al/Cu welded sample





# Microstructure - SEM

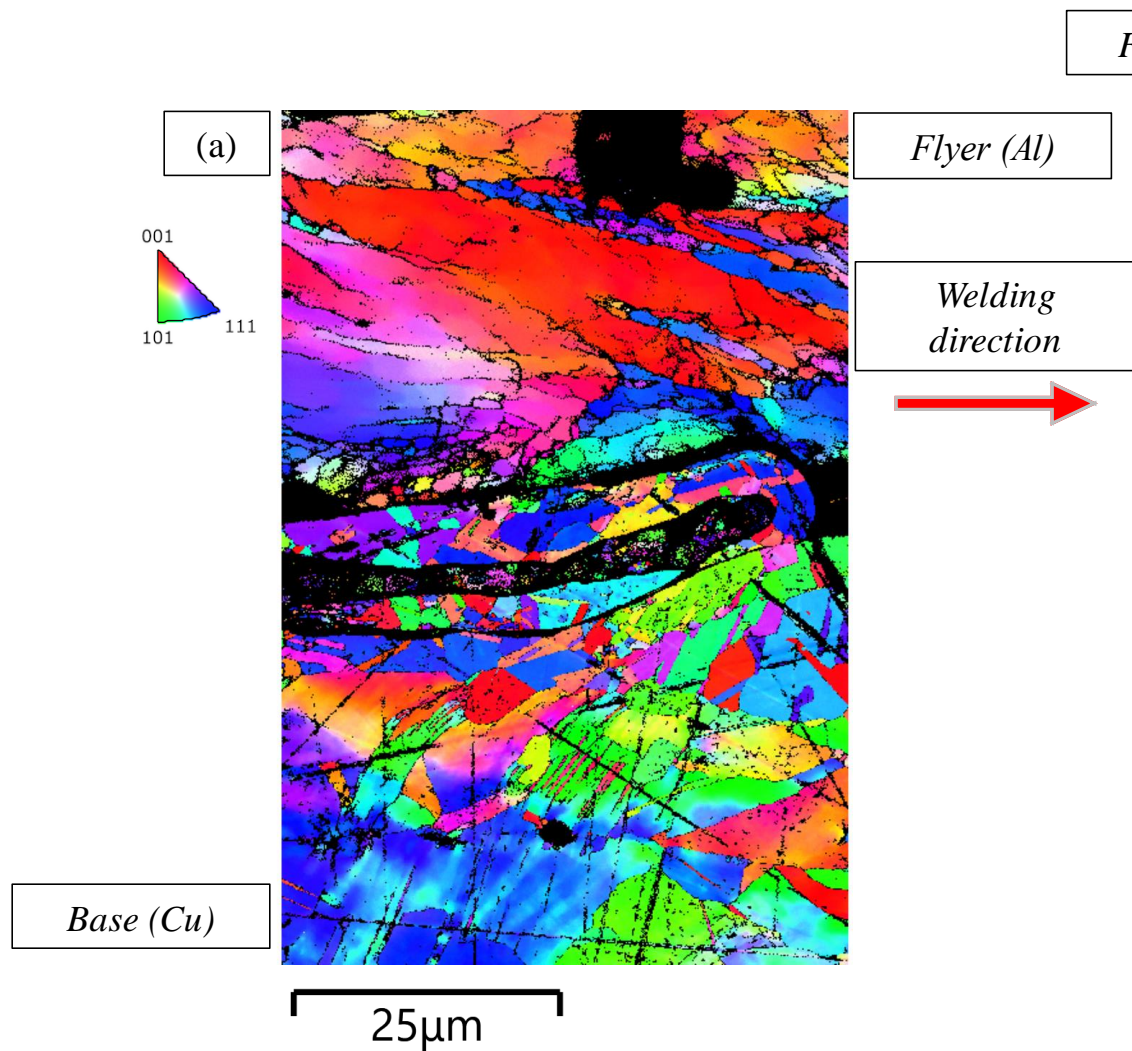
- Microstructure is modified by the MPW



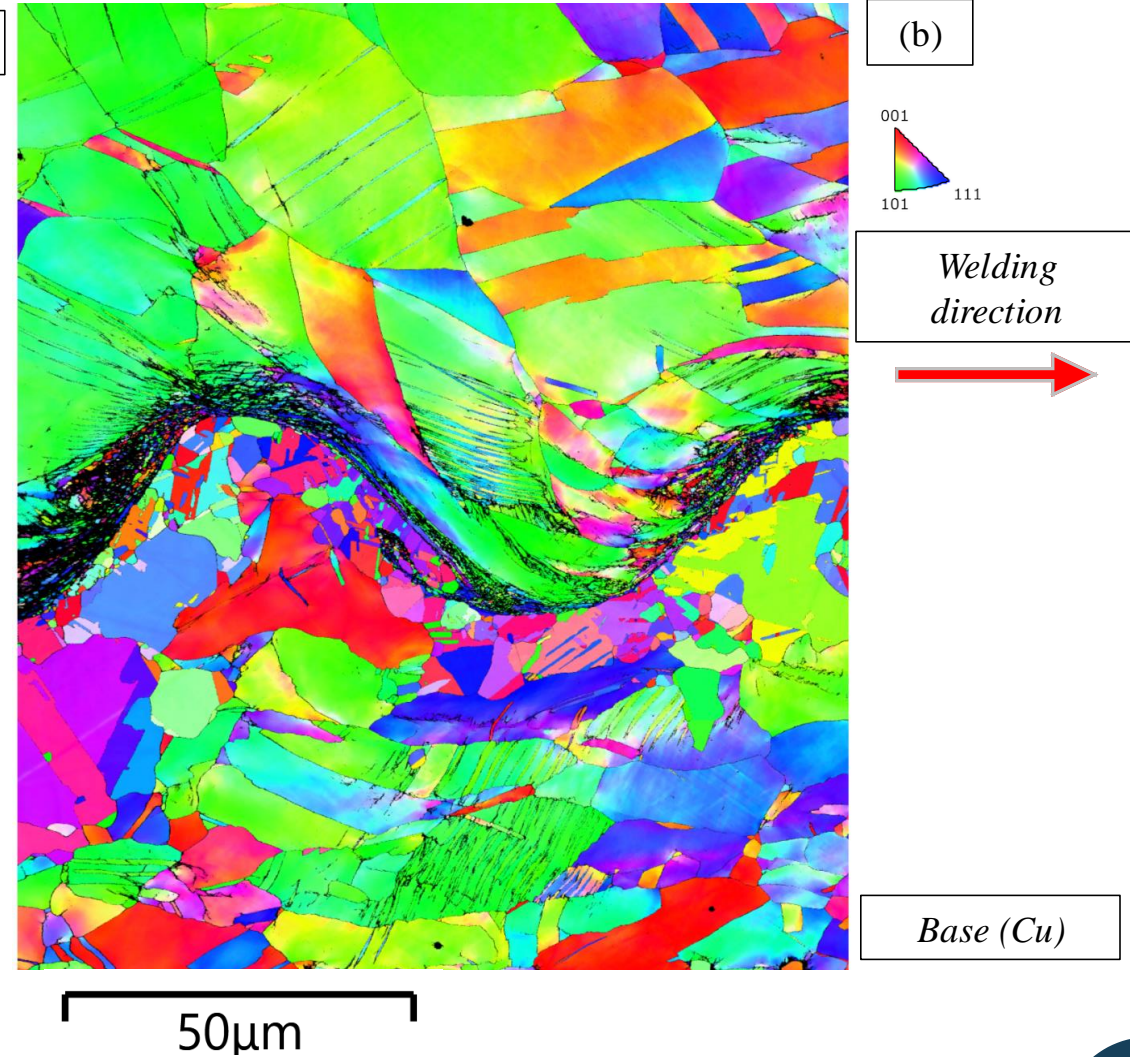
SEM images on JSM-7100F (Jeol) – (a) and (b) - Cu/Cu plates welded by MPW – Interface revealed after electro-polishing



# Microstructure - EBSD



EBSD image on JSM-7100F (Jeol) – (a) - Al/Cu plates welded by MPW – Wavy interface

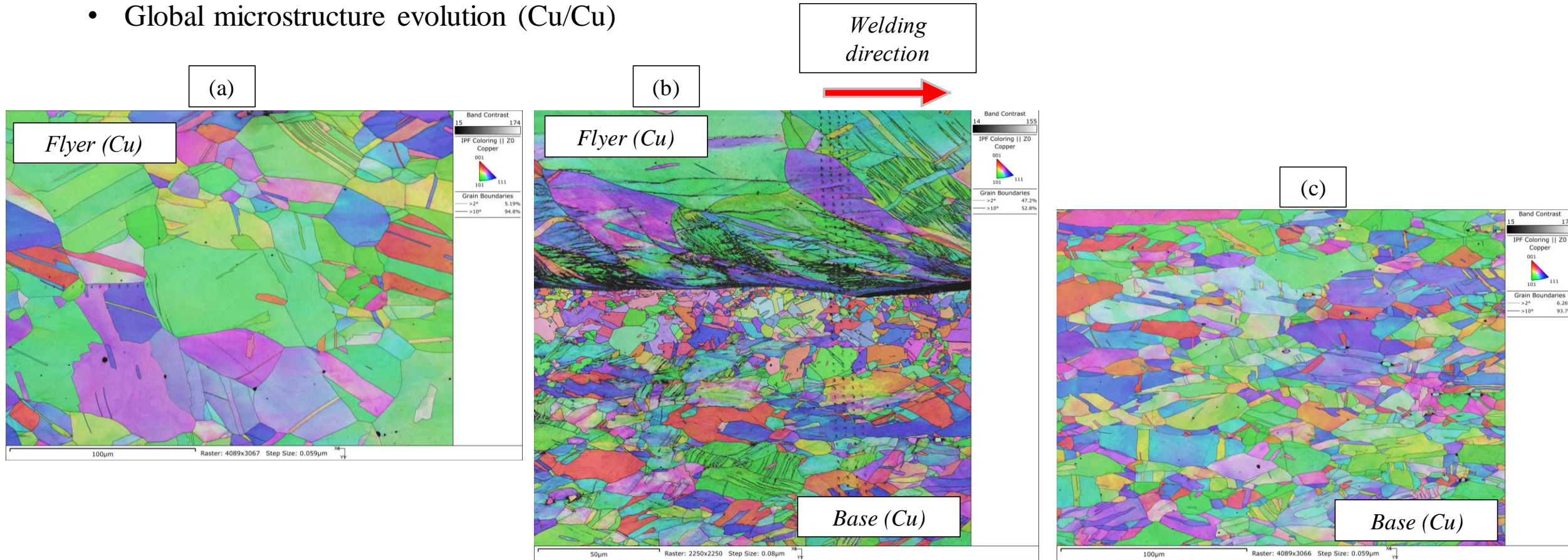


EBSD image on JSM-7100F (Jeol) – (b) - Cu/Cu plates welded by MPW – Wavy interface



# Microstructure - EBSD

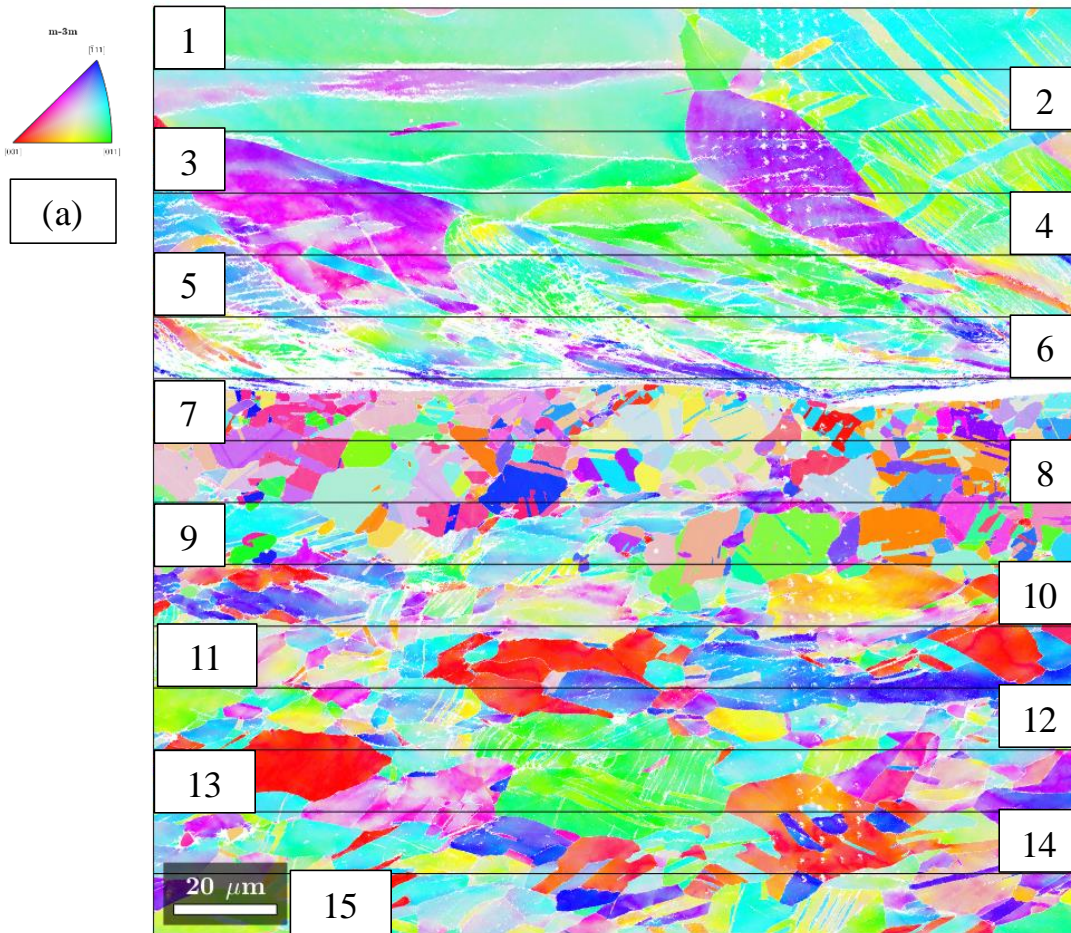
- Global microstructure evolution (Cu/Cu)



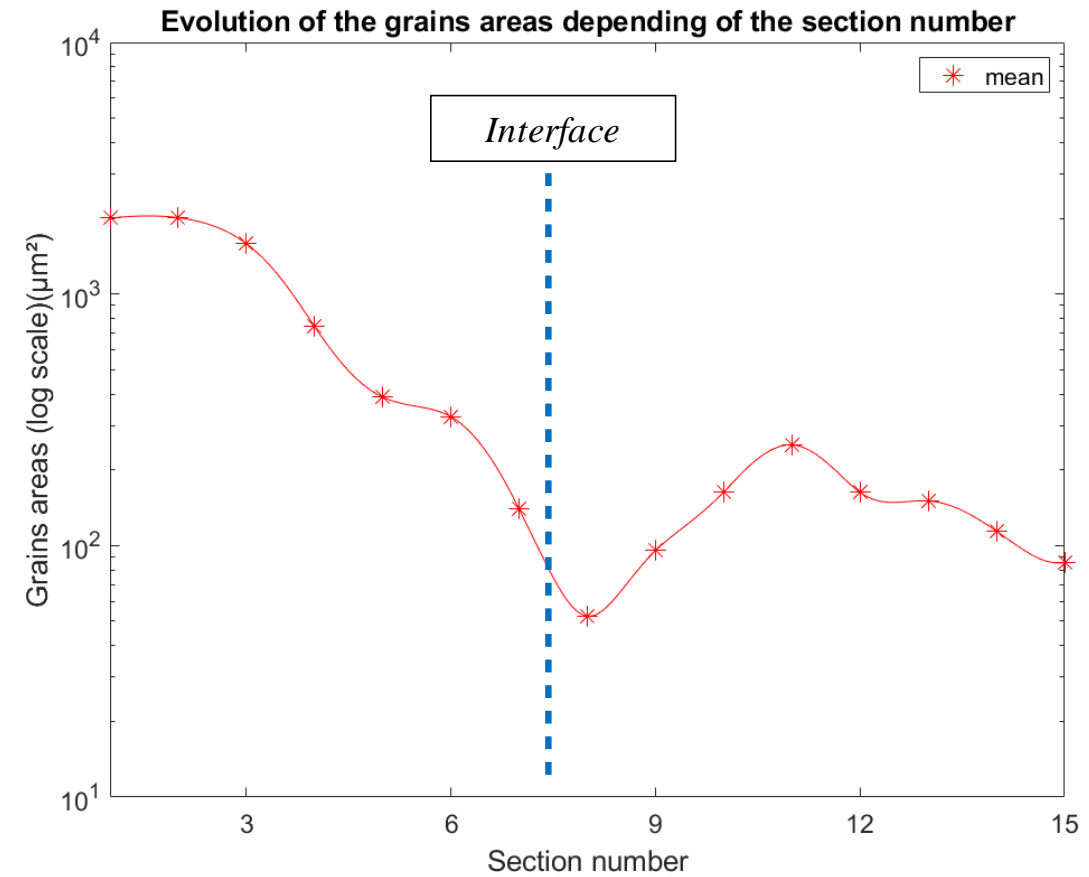
EBSD image on JSM-7100F (Jeol) – (a)(b)(c) – Cu/Cu plates welded by MPW – Microstructural comparison

# Microstructure - EBSD

- Local microstructure evolution on the interface



EBSD image on JSM-7100F (Jeol) – (a)– Cu/Cu welded by MPW –  
Position of the section number



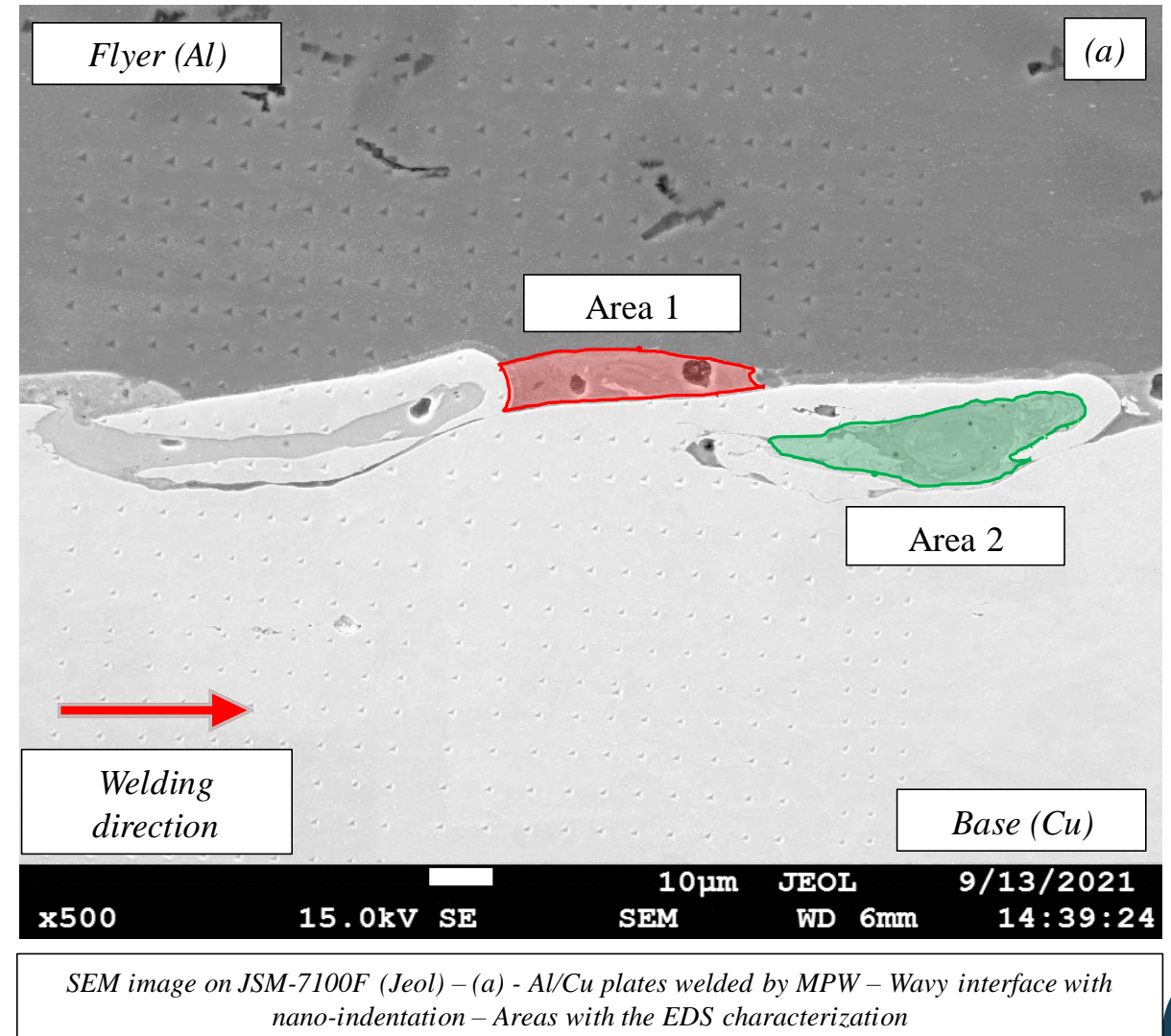


# Microstructure - EDS

- Different kind of intermetallic compounds present for Al/Cu samples

Elements	% Weigth	
	Area 1	Area 2
Copper (Cu)	53.2	65.8
Aluminum (Al)	46.8	34.2

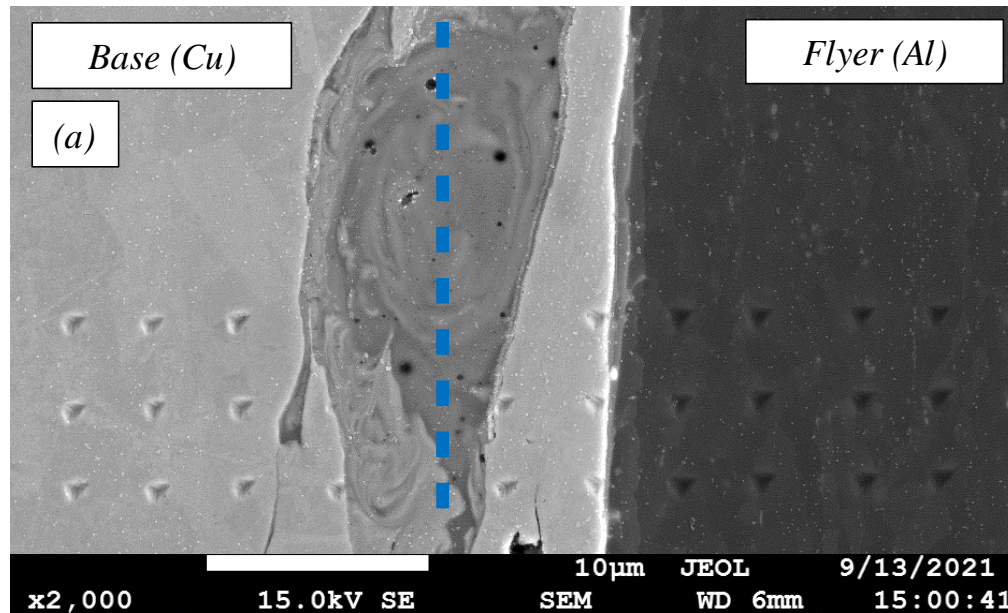
- Spatial diffusion very limited between Cu and Al  
 $\approx 2\text{-}3\ \mu\text{m}$  - no long range impact



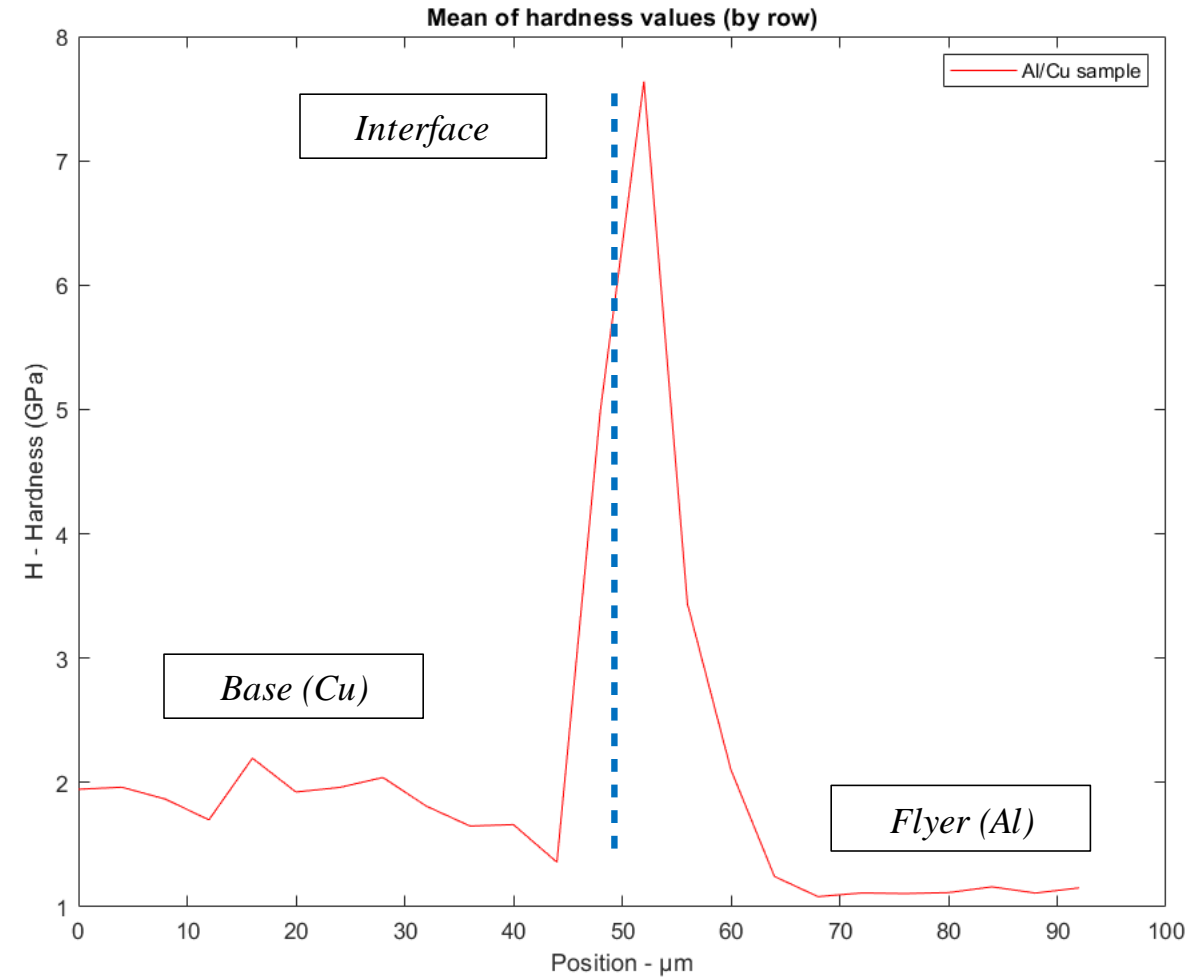
# Mechanical - Nanoindentation

- Al/Cu samples:

Intermetallics impact on the interface hardness



SEM image on JSM-7100F (Jeol) – (a) - Al/Cu plates welded by MPW – Wavy interface with nanoindentation (nanoindenter – Hysitron TI980 – Bruker)



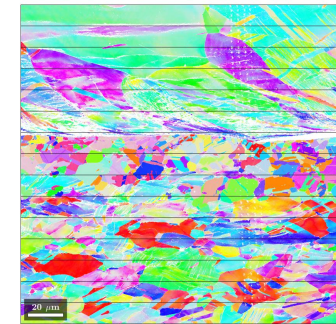
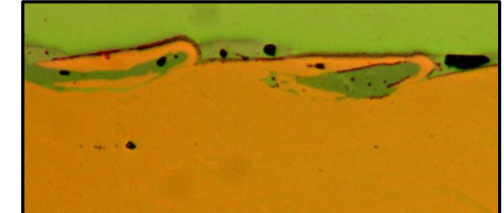
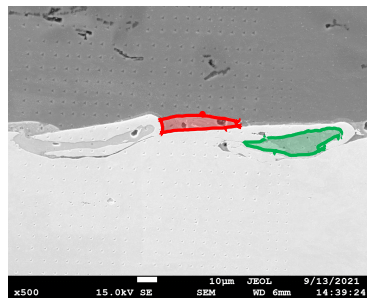
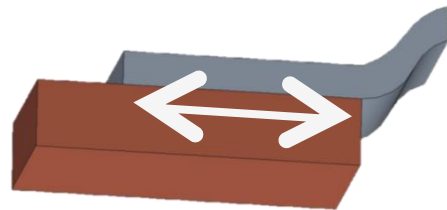


# Conclusion

- Conclusion:
  - Different intermetallic compounds composition
  - Important local hardness variation across the interface (Al/Cu)
  - Local modification for the grains size at the interface (Cu/Cu)
  - Effective welding “length” is varying along the welding seam
  
- Outlook:
  - Characterization of the different intermetallics compounds and local characterization of the welding seam
  - Determination of the global effective welded area
  - Deeper analysis for grain sizes and orientation

# Questions?

Thanks you for your attention – Any questions?



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